

**Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (Currently Amended):

An LCD monitor, comprising:

a circuit device, having plural electrodes on one side thereof;

plural bumps, respectively disposed on the electrodes;

a substrate, having plural first pads and plural second pads in accordance with the bumps;

a means of connection, comprising a plurality of conductive particles, conducting the bumps and the pads with the conductive particles bonded between; and

a barrier structure disposed on the side of the circuit device, the barrier structure being higher than the bumps without contacting the substrate to separate ~~separating~~ the conductive particles, wherein the barrier structure comprises a plurality of first barrier ribs extending along a first direction to form a partition between the bumps corresponding to the first pads, a plurality of second barrier ribs extending along the first direction to form a partition between the bumps corresponding to the second pads and a plurality of third barrier ribs extending along a second direction to form a partition between the bumps corresponding to the first and the second pads.

Claim 2 (original): The LCD monitor of Claim 1, wherein the barrier structure is made by an isolating material.

Claim 3 (previously presented): The LCD monitor of Claim 2, wherein the first pads are input terminals of the LCD monitor, and the second pads are output terminals of the LCD monitor.

Claims 4-6 (canceled).

Claim 7 (previously presented): The LCD monitor of Claim 1, wherein the first and the third barrier ribs are connected, having a plurality of L-shaped structures.

Claim 8 (previously presented): The LCD monitor of Claim 1, wherein the first and the third barrier ribs are connected, having a plurality of separated T-shaped structures.

Claim 9 (previously presented): The LCD monitor of Claim 1, wherein the second and the third barrier ribs are connected, whereby having a plurality of L-shape structures.

Claim 10 (previously presented): The LCD monitor of Claim 1, wherein the second and the third barrier ribs are connected, having a plurality of separated T-shaped structure.

Claim 11 (original): The LCD monitor of Claim 2, wherein the isolating material is polyimide (PI).

Claim 12 (original): The LCD monitor of Claim 2, wherein the connecting means is an anisotropic conductive film.

Claim 13 (original): The LCD monitor of Claim 2, wherein the bump is made of one metal selected from the group consisting of Au, Cu, Ni, and Zn.

Claim 14 (original): The LCD monitor of Claim 2, wherein the substrate is made by glass.

Claim 15 (original): The LCD monitor of Claim 2, wherein the circuit device is an integrated circuit.

Claim 16 (original): The LCD monitor of Claim 2, wherein the circuit device is a flexible printed circuit.

Claim 17 (Currently Amended):

A semiconductor device, comprising:

an electrode disposed on a base surface;

a bump disposed on the electrode;

a pad comprising plural first pads and second pads;

a connecting means, comprising a plurality of conductive particles, whereby conducting the bump and the pad with the conductive particles bonded between; and

a barrier rib disposed on the base surface, the barrier rib being higher than the bumps to separate ~~separating~~ the conductive particles, wherein the barrier rib comprises a plurality of first barrier ribs extending along a first direction to separate the conductive particles between the first pads, a plurality of second barrier ribs extending along the first direction to separate the conductive particles between the second pads and a plurality of third barrier ribs extending along a second direction, separating the conductive particles between the first and the second pads.

Claim 18 (previously presented):

The semiconductor device of Claim 17, wherein the barrier rib is made by an isolating material; the first pads are input terminals of a LCD monitor, and the second pads are output terminals of the LCD monitor.

Claim 19 (previously presented):

The semiconductor device of Claim 18, wherein the first and the second barrier rib are respectively connected to the third barrier rib, having a plurality of L-shaped structures.

Claim 20 (previously presented):

The semiconductor device of Claim 18, wherein the first and the second barrier ribs are respectively connected to the third barrier rib, having a plurality of separated T-shaped structures.

Claim 21 (original):

The semiconductor device of Claim 18, wherein the isolating material is polyimide; the connecting means is an anisotropic conductive film; and the bump is made by one metal selected from the group consisting of AU, Cu, Ni, and Zn.

Claim 22 (Currently Amended):

A method for making a semiconductor device, comprising the steps of:  
providing a circuit device, wherein the circuit device is formed with plural electrodes on one side thereof;  
forming a protective layer on the side of the circuit device with the electrodes exposed;  
forming plural bumps on the protective layer in accordance with the electrodes, and conducting the electrodes and the bumps; and  
forming a plurality of first, second and third barrier ribs on the side of the circuit device, thereby separating the bumps, wherein the barrier ribs are higher than the bumps.

Claim 23 (previous presented)

The LCD monitor of claim 1, wherein the first barrier ribs are perpendicular to the third barrier ribs.

Claim 24 (previous presented)

The LCD monitor of claim 1, wherein the first barrier ribs are parallel to the third barrier ribs.